

TWSE:6515

穎崙科技股份有限公司
法人說明會

2026.05.26

免責聲明

本簡報及同時發佈之相關訊息所提及之預測性資訊，包括營運展望、財務狀況及業務預測等內容，係本公司基於內部資料及外部整體經濟發展現況所得之資訊。

本公司未來實際所可能產生的營運結果、財務狀況與業務成果，可能與預測性資訊有所差異。其原因可能來自各種因素，包括但不限於市場需求、價格波動、競爭態勢、各種政策法令與金融經濟現況之改變，以及其他本公司無法掌控之風險等因素。

本簡報中所提供之資訊，係反應本公司截至目前為止對於未來的看法，並未明示或暗示性地表達或保證其具有正確性、完整性或可靠性。對於這些看法，未來若有變更或調整時，本公司並不負有更新或修正之責任。

公司簡介

高雄總公司

成立日期

西元 2001 年 4 月 10 日

實收資本額

NTD 360,416,420

員工人數

1408人

董事長兼總經理

王嘉煌

服務項目

半導體測試介面研發設計及製造銷售

登記地址

高雄市楠梓區創意南路68號



美國分公司

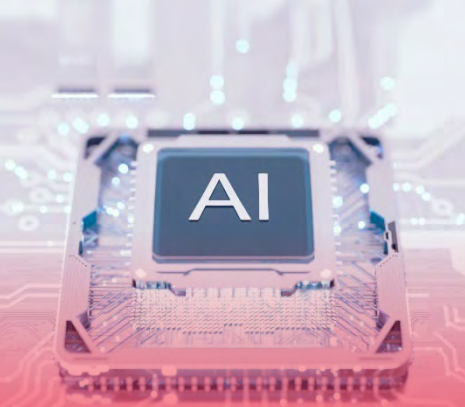


新竹分公司



經營理念

始終站在客戶的角度思考半導體測試需求，並透過客戶參與、技術創新、製造管理及供應鏈整合，持續堅持品質，服務全球，致力於為客戶、員工、供應商及股東創造最大的福利並善盡社會責任。



持續創新

透過技術創新
為客戶打造最佳
測試介面解決方案



堅持品質

提供整體解決方案
並於全球準時交付
超越客戶的品質要求



全球服務

致力成為全球領先的
專業測試服務供應商
在 IC 測試各階段提供最佳服務

簡報大綱

全球布局

產業趨勢

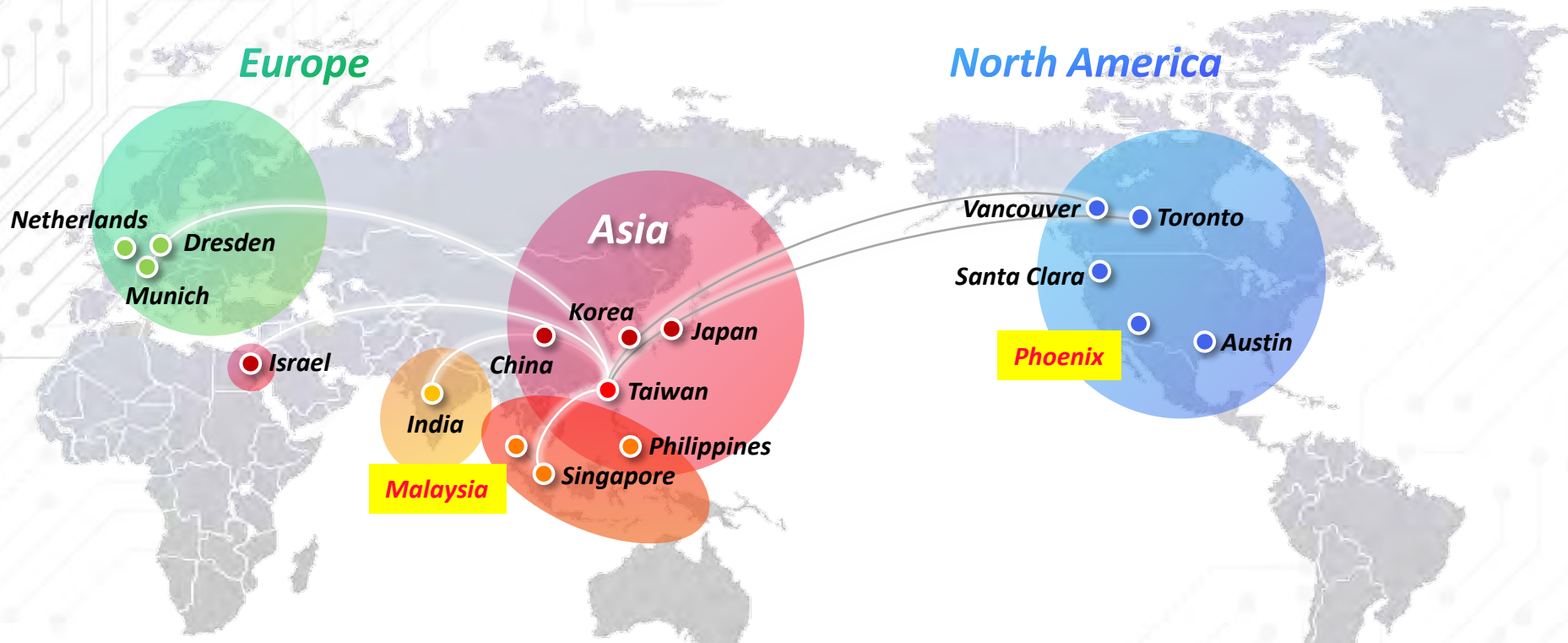
經營績效

研發創新



全球布局

技術創新 服務全球



高雄探針廠

Spring Probe
for Socket

高雄廠

Coaxial Socket
HyperSocket™

新竹廠

Vertical Probe Card
MEMS Probe Card

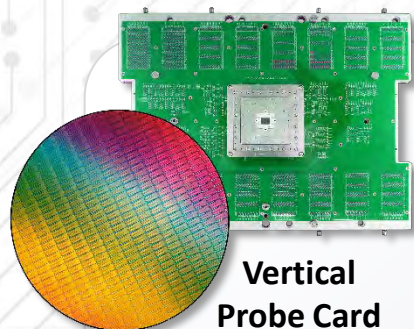
蘇州廠

Coaxial Socket

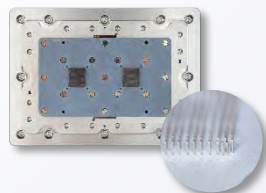
仁武廠

Coaxial Socket

Your Trusted Partner in Semiconductor Testing



Vertical
Probe Card



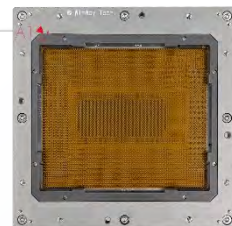
MEMS Probe Card



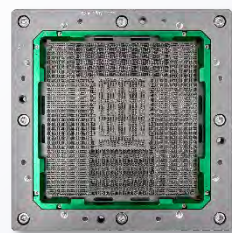
Coaxial Socket



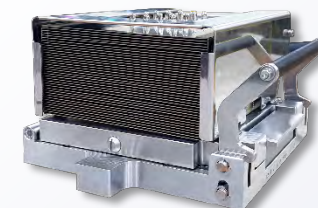
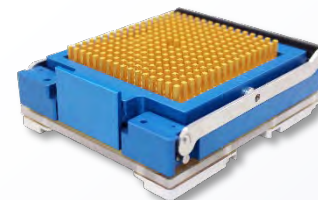
PoP Socket



HyperSocket™



Coaxial Socket



Production
Burn-in Socket

晶圓測試

Wafer Sort

最終測試

Final Test

高頻高速
系統測試

SLT & SFT

高速
老化測試

Functional
Burn-in

DFT Design For Testing **DFM** Design For Manufacturing

全球客戶營收概況

First 4 Months of 2026

North American

81%

China

7%

Taiwan

12%

Top10 Customers

90%

- AI
- HPC
- ASIC
- CPU
- GPU
- AP

Active Customers

200+

- IC Design
- CSP
- Foundry
- ASIC
- OSAT
- IDM

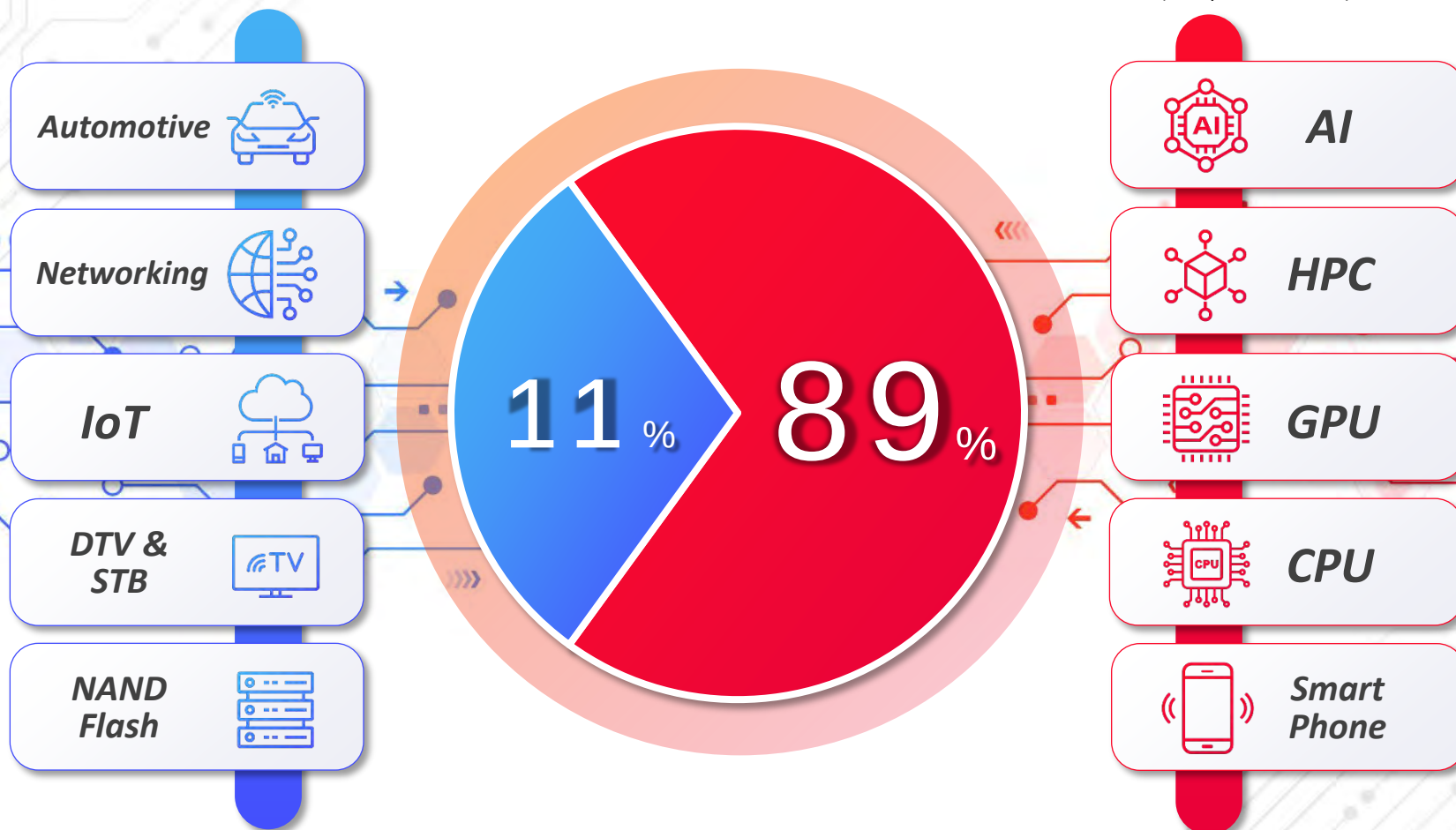
客戶先進製程占比續增

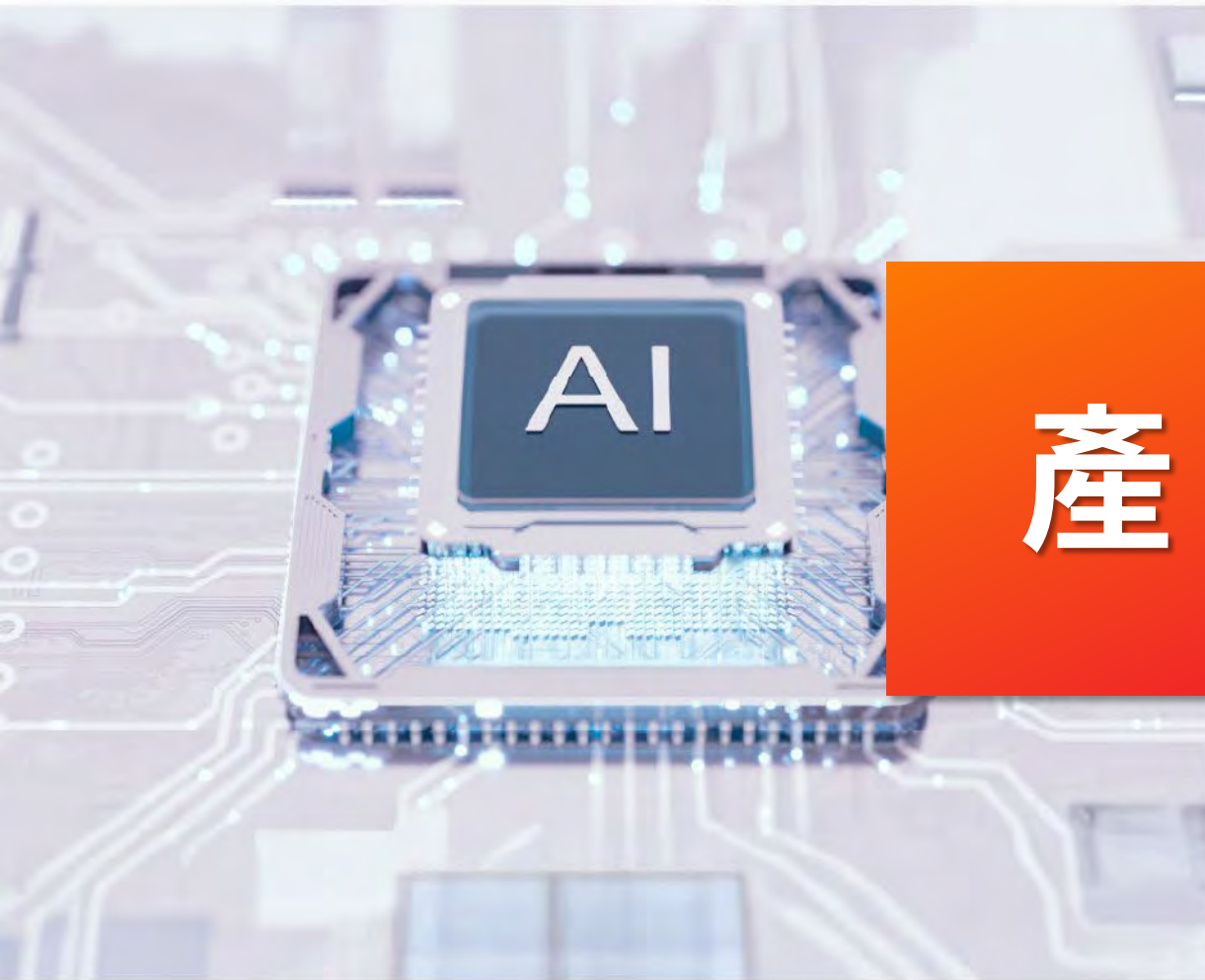
First 4 Months of 2026

Mature Node

Advanced Node

7nm (or equivalent node) and below





產業趨勢

AI驅動未來產業價值鏈

應用 Applications

- AI Agent
- LLM / Gen AI
- AI PC
- Humanoid Robot
- Smart Factory
- Self-driving car
- AR/VR
- Digital Twins
- Smart City

模型 Models

- AI Framework
- Foundation Model
- MLOps / Platform
- AI Training Platform

基礎設施 Infrastructure

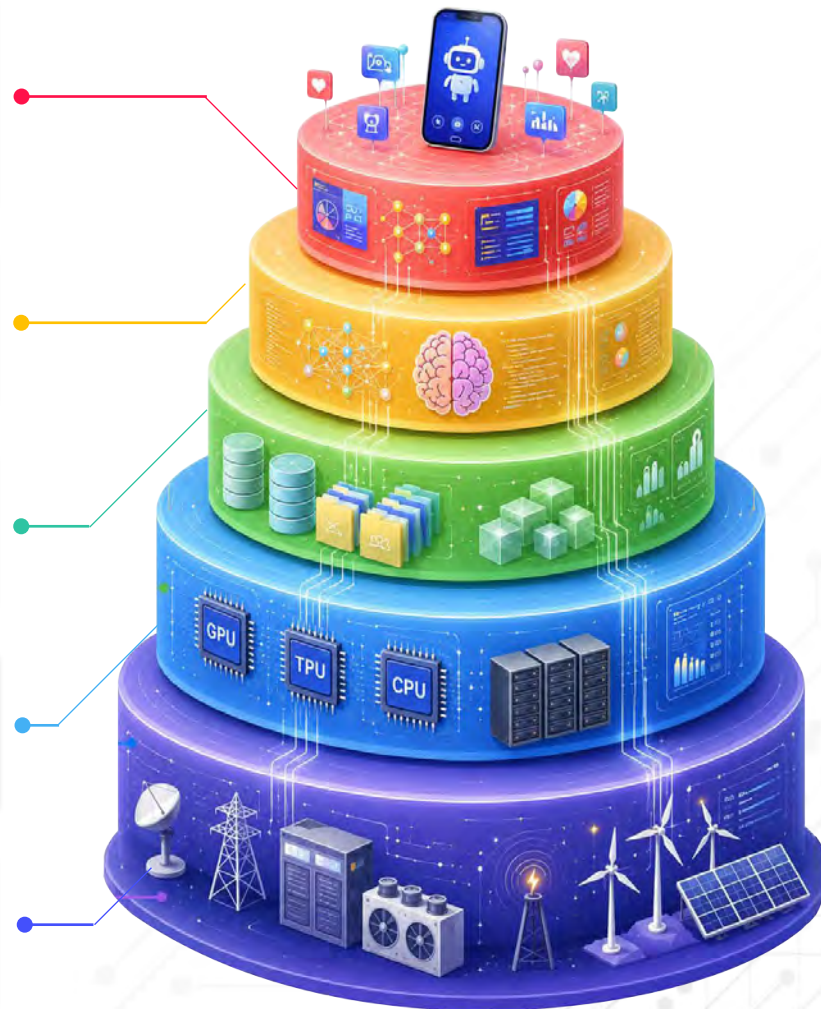
- AI Factory
- Liquid Cooling
- Hyperscale Datacenter
- Optical Network

晶片 Chips

- GPU
- XPU
- AI ASIC
- CPU
- CoWoS / SoIC
- HBM
- Chiplet
- CPO / CPC

能源 Energy

- Power Delivery
- Green Energy
- Electric power



Source : NVIDIA

半導體產業核心驅動力

Agentic AI



Collaborative Robots



AI
PC & Phone



Edge
Computing



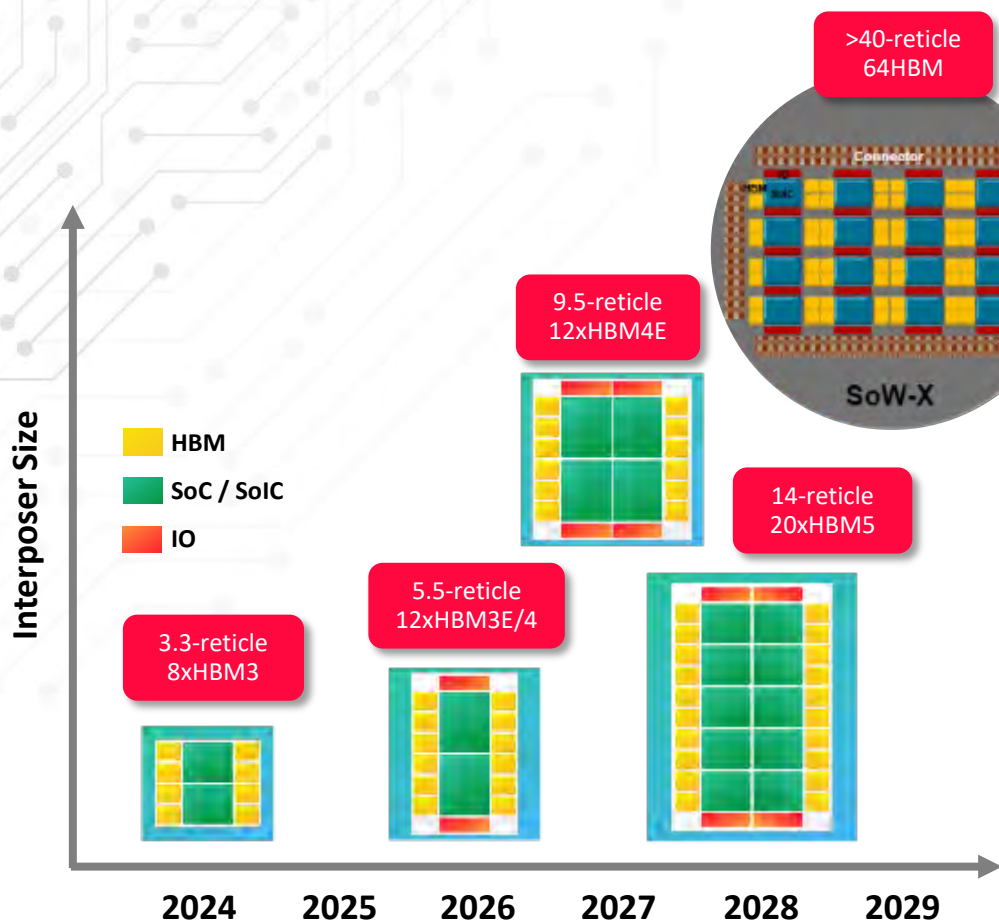
High Speed
Networking



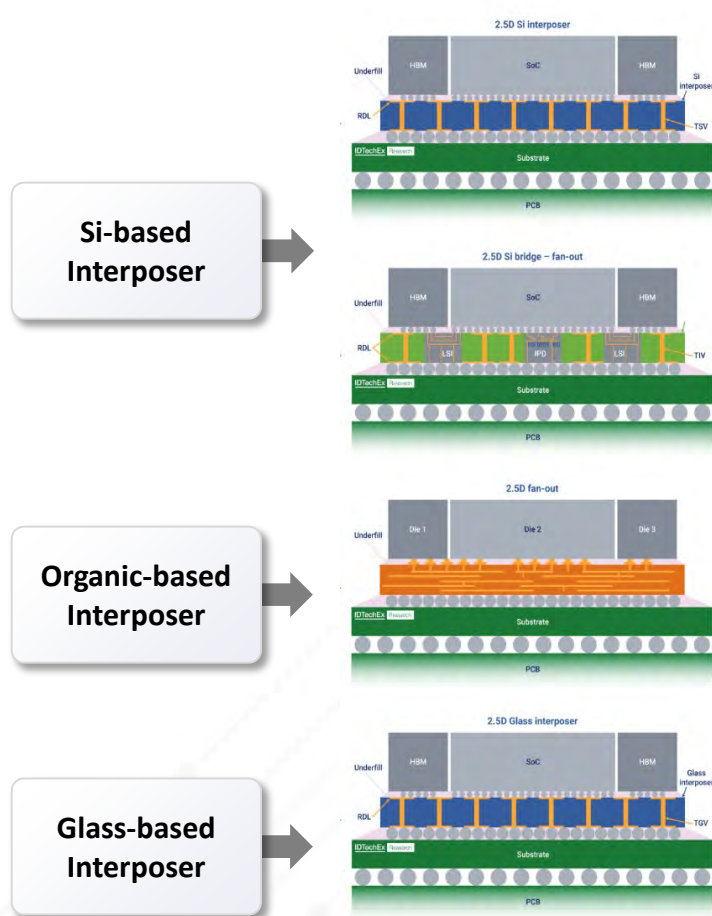
Data Center



封裝技術再進化 突破效能極限



Source : TSMC



Source : IDTechEx Research

先進封裝推動高階測試需求



半導體測試介面商機與挑戰

晶圓測試

Wafer Sort (CP - Circuit Probe)



- K.G.D

Cobra Probe Head

MEMS Probe Head

最終測試 FT(Final Test)



- CPO/CPC substrate
- Optical Engine
- WMCM/SiP/MoP

Coaxial Socket

PoP Socket

高頻高速系統測試

SLT (System Level Test) , SFT

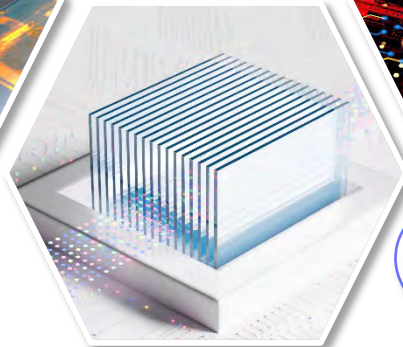


- 2.5D&3D PKG
- WMCM/SiP/MoP
- CPO Module

HyperSocket™

Coaxial Socket

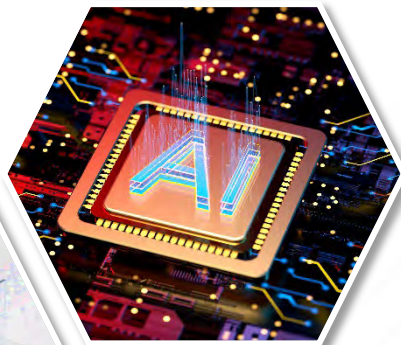
高速老化測試 (Functional Burn-in)



Production Burn-in

Functional Burn-in

溫控設備 (Thermal System)

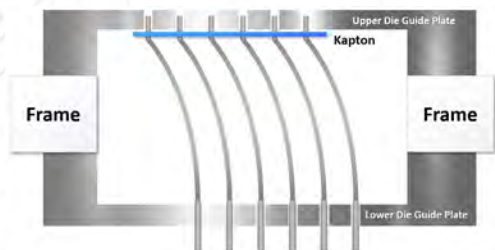


Liquid Cooling
HyperSocket™

Active Thermal
Controller

晶圓測試將成IC測試挑戰

At Speed Test and K.G.D

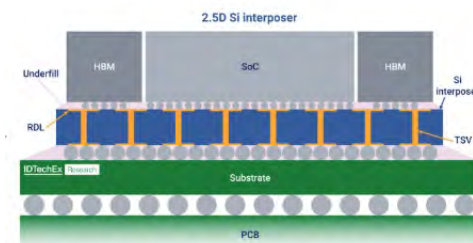


Cobra



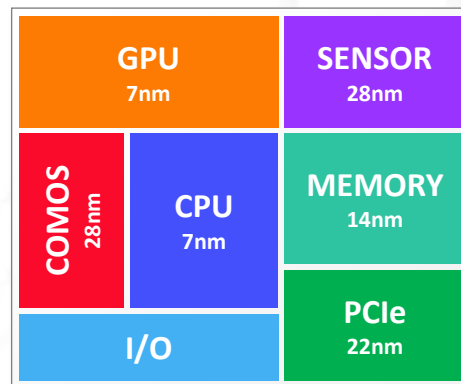
MEMS

Pin Count	Less, limited to probe force design	★ Higher (More flexible to design)
CCC(A)	2.2 @ 4mil probe diameter	★ 2.2 @ 3mil probe diameter
High Speed	32G	★ 112G
Force(g)	2~25	★ 1.5 ~ 4.5
Pitch (um)	80~200	★ 40~200
Operating Temp.	- 50°C to 150°C	★ - 50°C to 175°C



Source : IDTechEx Research

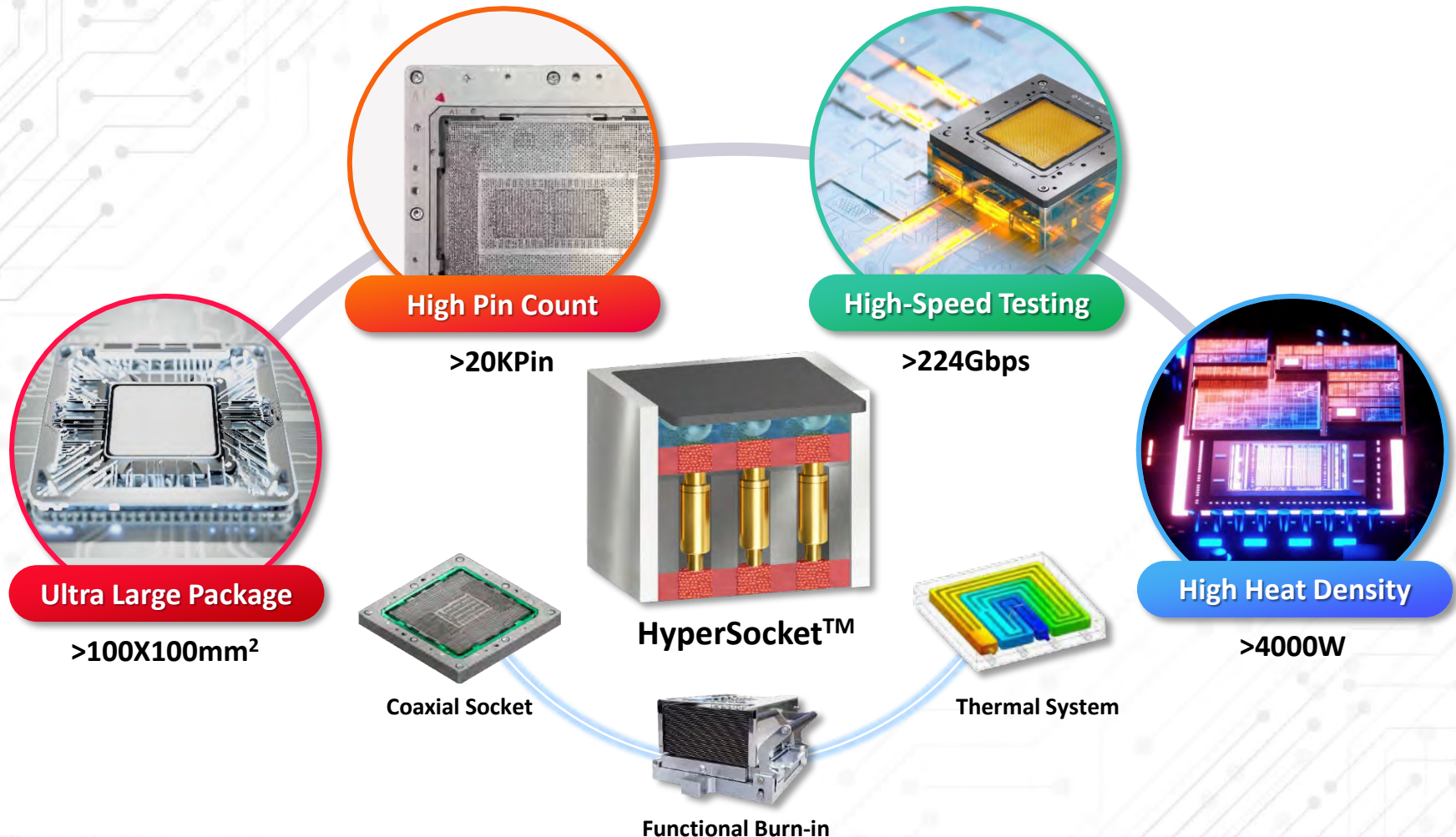
Chiplet Multiple Probe Card Demand



Source : Trend Force

AI 持續帶動系統測試高速成長

Comprehensive solution for all test insertions





經營績效

營收獲利持續成長

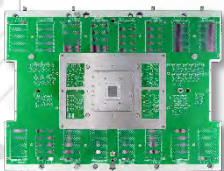
2025
現金股利
(NTD)

50

(NTD MILLION)	1Q26	4Q25	1Q25	1Q26 Over 4Q25	1Q26 Over 1Q25
營業收入	2,980	2,234	2,297	+33%	+30%
營業毛利率	43%	42%	49%	+1ppts	-6ppts
營業費用	505	457	393	+11%	+29%
營業淨利率	26%	21%	32%	+5ppts	-6ppts
本期淨利	699	483	613	+45%	+14%
純益率	24%	22%	27%	+2ppts	-3ppts
每股盈餘 (NTD)	19.54	13.53	17.21	+44%	+14%

2026產品組合

First 4 Months of 2026



Probe Card

27 %



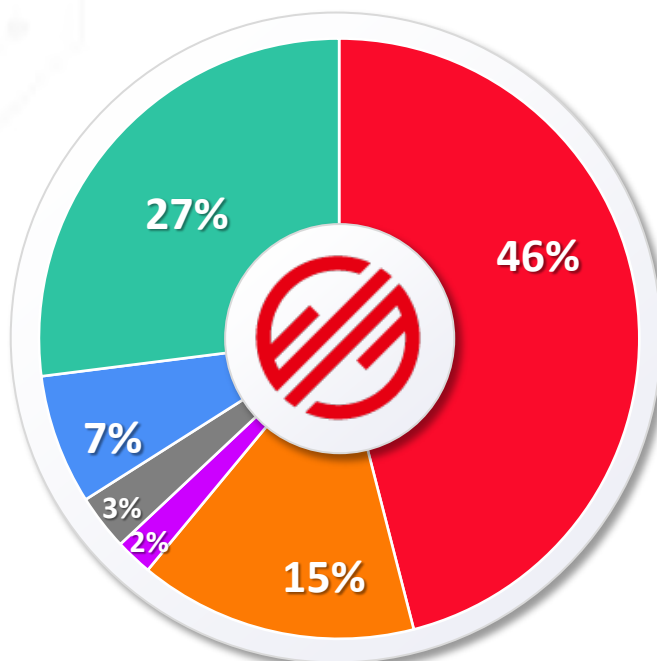
Contact
Element

7 %



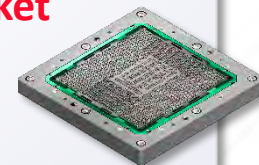
Others

3 %



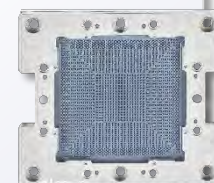
Coaxial Socket

46 %



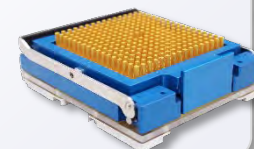
PoP & Plastic
Socket

15 %



Burn-in Socket

2 %

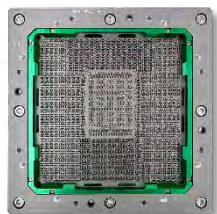


產品應用廣泛

First 4 Months of 2026



HyperSocket™



Coaxial Socket

HPC & AI
68 %

Networking
Auto / Others

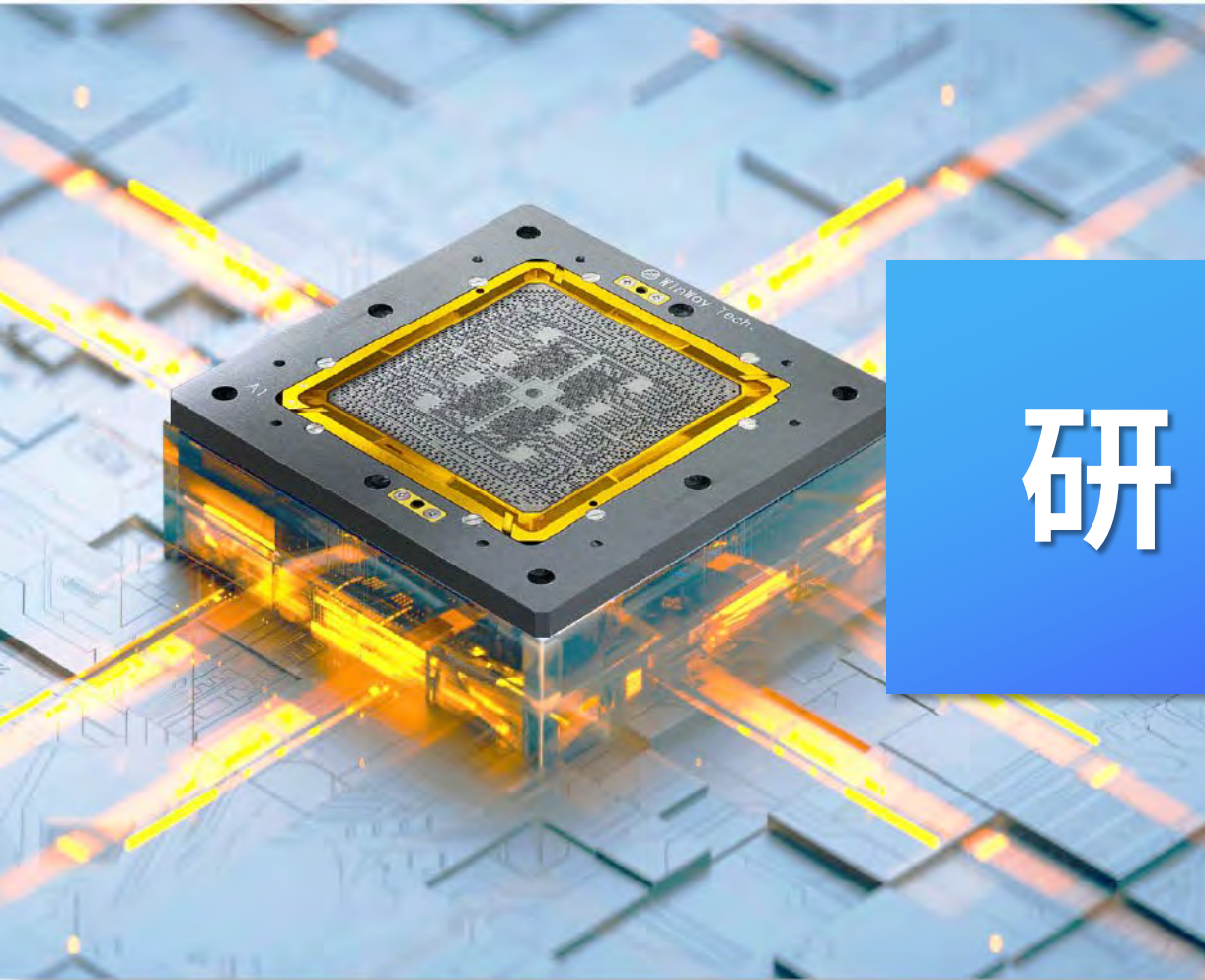
22 %
Plastic Socket

Smart Phone

8 %
POP Plastic Socket

PC & Gaming

2 %
POP Plastic Socket



研發創新

高階測試座革新半導體測試方案

雙層超導 HyperSocket™

Patent NO.

TWI862047
TWI884802
TWI862191
TWI901161
TWI922268
TWI923382
CN220584352

Patent Pending

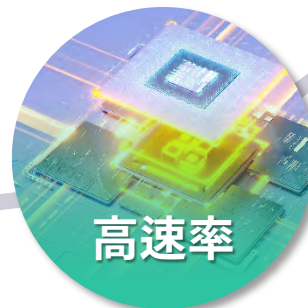
USA
Malaysia



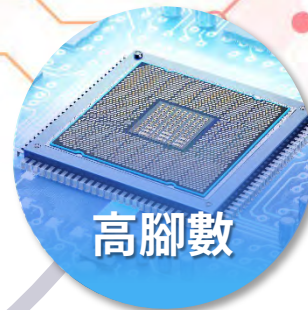
- 加大接觸面積
- 提升散熱效益
- 提高測試穩定性



- 平行電流路徑
- 大幅降低溫升



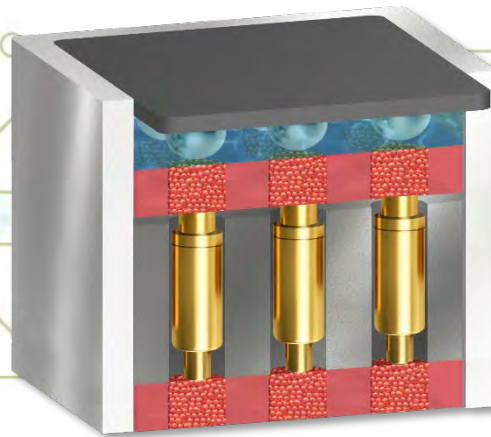
- 全金屬屏蔽，短迴路設計
- 滿足224Gbps以上測試



- 零預壓創新設計
- 延長維護週期

全球首推半導體液冷測試方案

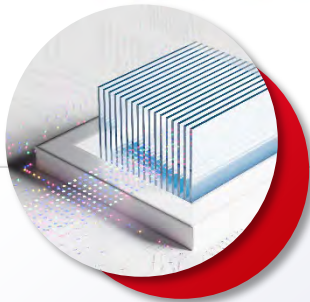
高電流液冷 Liquid Cooling Socket



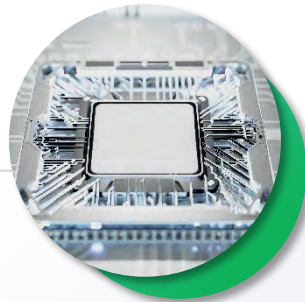
Patent NO.

TWI901181

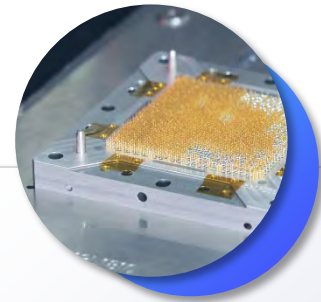
US12625162



提升測試散熱效率



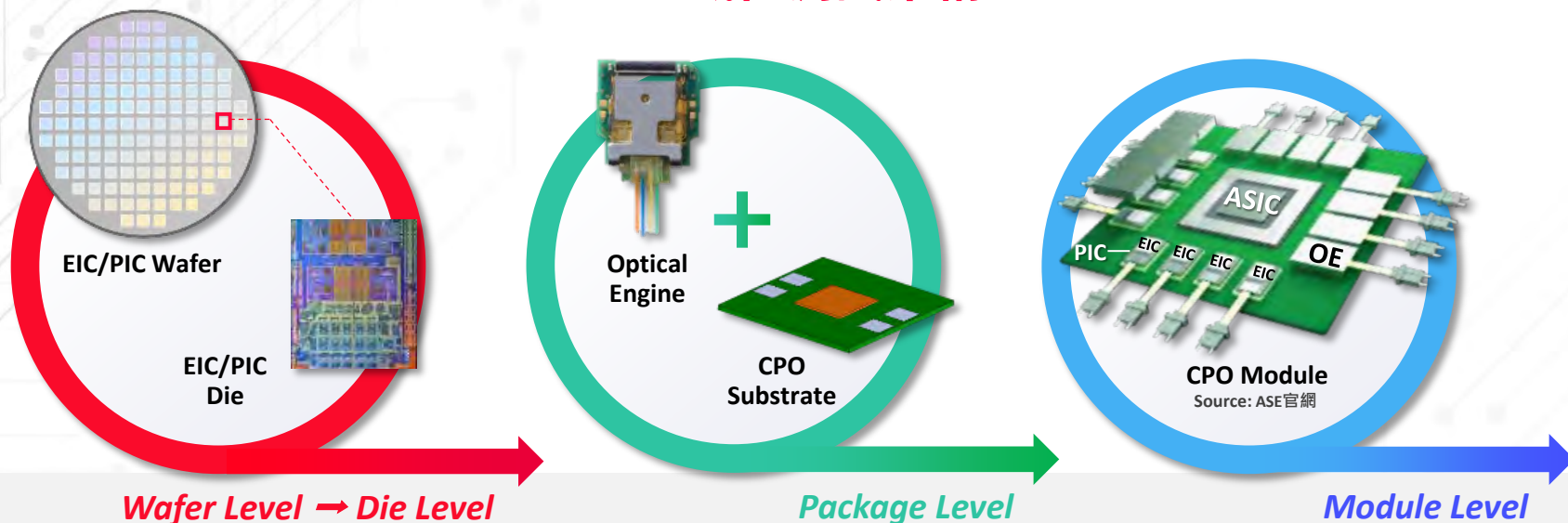
提高先進封裝
測試穩定性



延長探針使用壽命

矽光子CPO測試方案全面導入

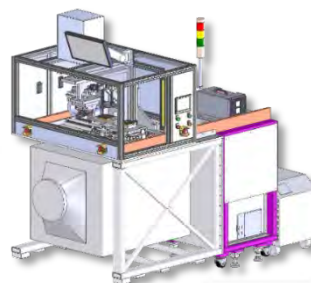
CPO 全域性測試架構



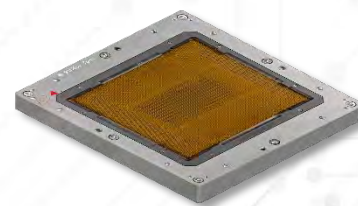
WLCSP Probe Head
(PIC & EIC Wafer test)



Optical and Electrical
Test Socket
(Optical Engine)



Double Sided
Probing System



HyperSocket™

全球首推超高功率溫控方案

E-Flux6 3500W 液冷溫控系統

AI 晶片帶動高功率散熱需求



自製探針產能持續擴充



成本優化

自製率提升，優化毛利結構



技術自主

掌握關鍵製程技術，優化探針特性



品質控管

產品品檢嚴謹，卓越客戶體驗

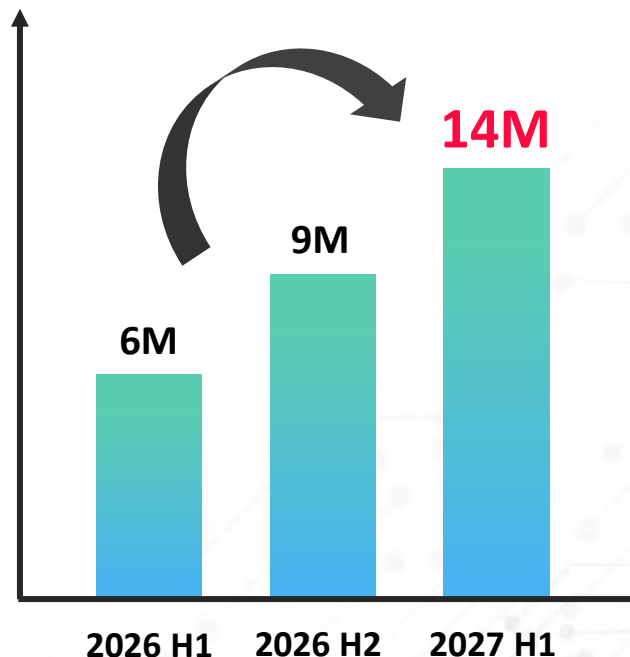


交期彈性

物料彈性調度，快速應變需求

WinWay Spring Probe Capacity

Pin / Month



高雄仁武廠 Socket產線加速擴增

仁武一廠

2026 年 4月 開始投產

仁武二廠

動土日 2026 年 5月 29 日

預計投產 2027 Q2

總面積約 **6300** 坪

WinWay Socket Capacity

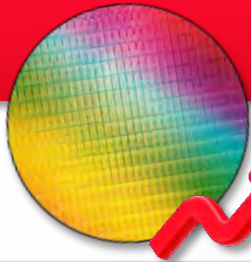
Set / Month

5,000-pin equivalent sockets



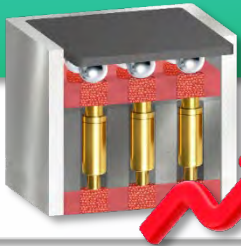
先進製程與封裝複雜度倍增

CoWoS、CoPoS、CPO



Fab and OSAT expansion drive equipment demand

Longer and Longer Fab In-process Time



HyperSocket™ -DH

Bigger and Bigger Device Package

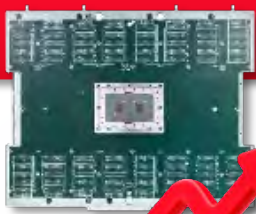
Higher and Higher Device Power Consumption



Functional Burn-In Requirement

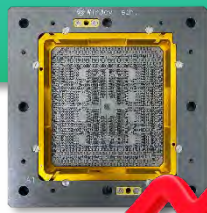
More Reliability Test Insertion

半導體測試時間大幅增加



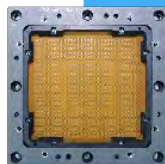
MEMS and Cobra Probe card

Longer Wafer Sort Test Time



Plastic, Coaxial and HyperSocket™

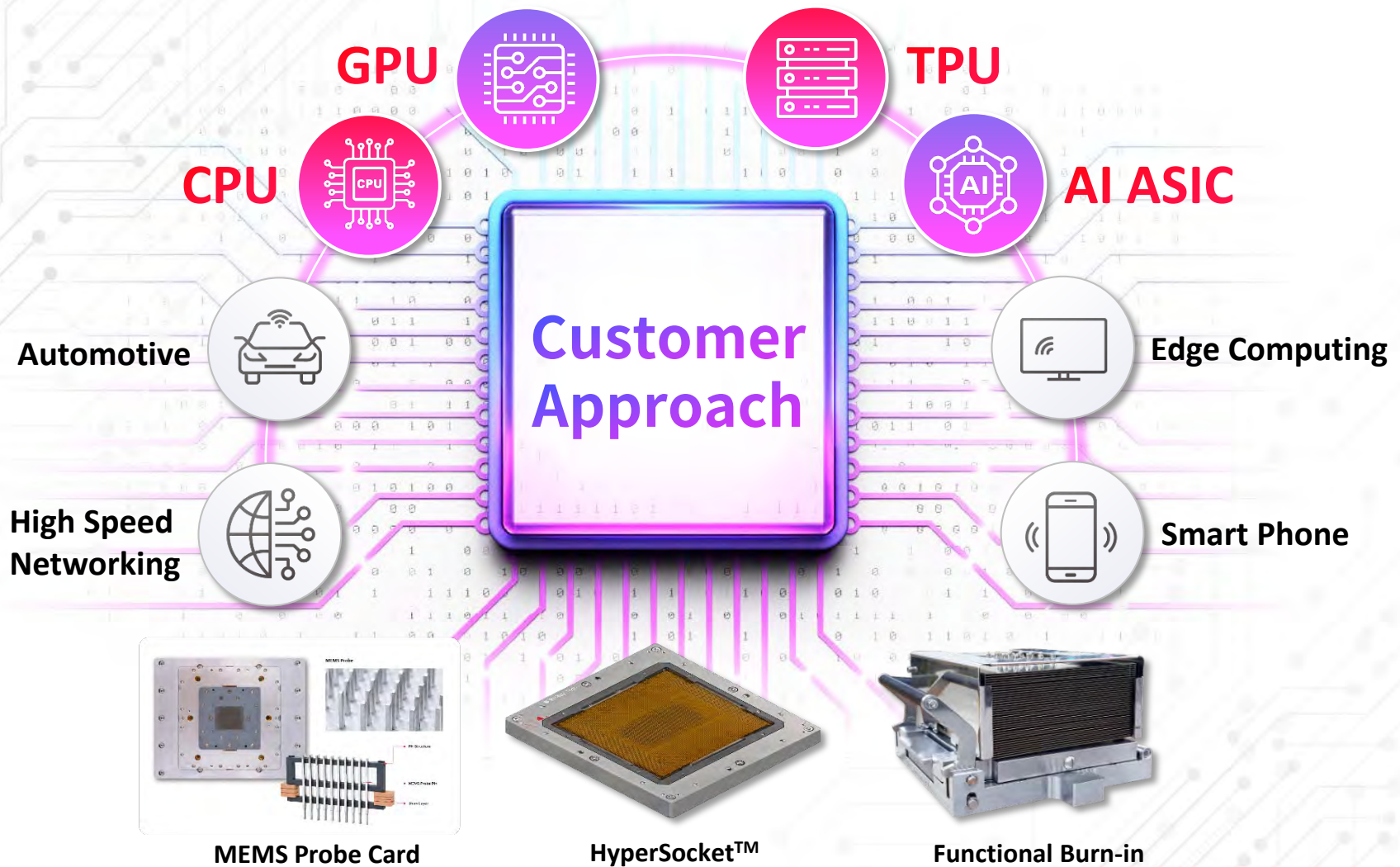
Longer FT (ATE) Test Time



Coaxial and HyperSocket™

Longer SLT Test Time

半導體多元應用驅動營收長期成長





仁武產業園區廠房動土典禮

2026.05.29

仁武產業園區

高雄市仁武區仁發六路6號對面



2026年度股東會

2026.06.17

莊敬堂

高雄市楠梓區加昌路600號

TWSE:6515

Q&A

TWSE:6515

**THANK
YOU**

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